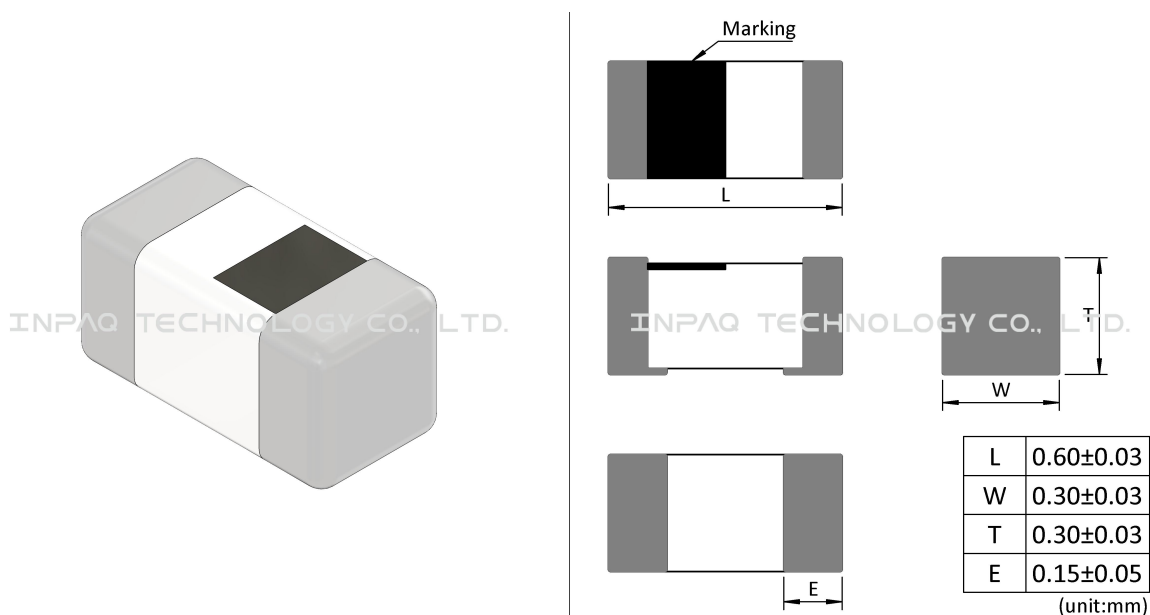


MCI0603MZ1N3_HBP



Appearance & Shape



注意 NOTICE: All Specifications are subject to change without notice.

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2. 本文件僅說明參考標準規格，如需訂購，請依實際核准所需規格進行申辦。

Specification

L size(mm)	0.6±0.03
W size(mm)	0.3±0.03
T size(mm)	0.3±0.03
Size code Inch(mm)	0201(0603)
Inductance(nH)	1.3
Tolerance	B(±0.1nH), C(±0.2nH), S(±0.3nH)
Test Frequency(MHz)	500
DCR(Ω) Max.	0.15
I _{rms} (mA) Max.	600
Q Value (Min.)	14
SRF(MHz) Min.	17000
Operating Temperature range(including self-temperature rising) °C	-55~+125

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Notices

- Particular ceramic material and coil structure provide high frequency application range up to 20GHz.
- Small size and low profile.
- Excellent solderability and heat resistance.

Packing

Packing Reel(Inch)	Packaging type	Standard package quantity(PCS)	Piece weight(gram)	MSL Level
7	Paper type	15000	0.000183	1

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